

IN THE CLAIMS

A complete set of the existing claims are set forth below, with the amended claims showing deletions (strikethrough) and insertions (underline).

1. (currently amended) A photonic package comprising:
a housing;
a semiconductor light source disposed within the housing, the semiconductor light source having a first output and a second output;
a first reflective surface disposed inside the housing selected from one of a side wall of the housing and an interior surface of a cover of the housing to reflect said second output;
a second reflective surface to deflect the second output to the first reflective surface; and
a photodetector disposed within the housing adapted to indirectly receive said second output of the semiconductor light source reflected off said first reflective surface.
2. (original) The photonic package of claim 1, wherein the photonic package comprises an optical transponder.
3. (currently amended) The photonic package of claim 1, wherein the first reflective surface comprises an exterior surface of an elevated substrate angularly disposed relative to the second output, to reflect said second output to said photodetector.
4. (currently amended) The photonic package of claim 1, wherein the second reflective surface ~~photonic package further comprises a reflective mirror to angularly reflect the second output.~~
5. (currently amended) The photonic package of claim 4, wherein the first reflective surface is optically coupled to said reflective mirror to further reflect the second output to said photodetector.

6. (previously cancelled)
7. (original) The photonic package of claim 1, wherein the first output is provided from a front facet of the semiconductor light source.
8. (original) The photonic package of claim 1, wherein the second output is provided from a back facet of the semiconductor light source.
9. (original) The photonic package of claim 1, wherein the photodetector comprises a photodiode.
10. (original) The photonic package of claim 9, wherein the photodiode comprises a p-i-n junction photodiode.
11. (currently amended) The photonic package of claim 1, wherein further said first reflective surface comprises a reflective coating.
12. (original) The photonic package of claim 11, wherein the reflective coating comprises paint having a pigment of titanium dioxide.
13. (previously cancelled)
14. (previously cancelled)
15. (cancelled)
16. (currently amended) A method for forming a photonic package comprising:
providing a semiconductor light source to provide a first and a second output;

providing a first reflective surface to reflect the second output of the semiconductor light source, wherein said providing of a first reflective surface comprises providing a reflective interior surface to a housing of the photonic package;

providing a second reflective surface and disposing said second reflective surface in a manner such that said second reflective surface reflects said second output of the semiconductor light source to said reflective interior surface of the housing, for reflection to said photodetector.; and

adapting a photodetector to indirectly receive the second output of the semiconductor light source reflected from the interior surface.

17. (previously cancelled)

18. (previously cancelled)

19. (original) The method of claim 16, wherein said providing of a reflective surface comprises providing a substrate having an angular exterior surface, and the method further comprises disposing said substrate in a manner such that said angular exterior surface of the substrate reflects said second output of the semiconductor light source to said photodetector.

20. (cancelled)

21. (new) The method of claim 16, wherein said providing of a second reflective surface comprises of providing a mirror and disposing said mirror in a manner such that said mirror reflects said second output of the semiconductor light source to said reflective interior surface of the house, for reflection to said photodetector.

22. (new) A photonic package comprising:

a housing;

a semiconductor light source disposed within the housing, the semiconductor light source having a first output and a second output;

a first reflective surface disposed inside the housing to reflect said second output;
a second reflective surface to deflect the second output to the first reflective surface, at least one of said first and said second reflective surfaces is selected from one of a side wall of the housing and an interior surface of a cover of the housing; and
a photodetector disposed within the housing adapted to indirectly receive said second output of the semiconductor light source reflected off said first reflective surface.

23 (new) The photonic package of claim 21, wherein said at least one of said first and said second reflective surfaces comprises a mirror.